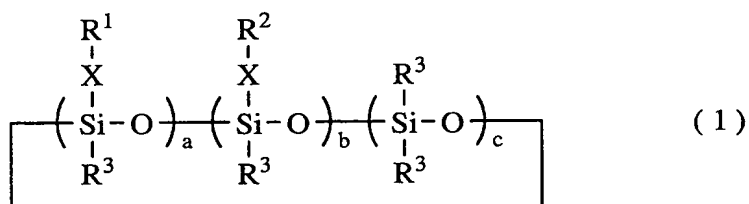


## Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

### Listing of Claims

1. (Original) A thermal conductive silicone composition comprising a siloxane containing a hydrolytic group represented by the formula (1):



where;

R<sup>1</sup>: a group containing an alkoxysiloxy group having 1 to 4 carbon atoms;

R<sup>2</sup>: a siloxane represented by the following formula (2) or a monovalent hydrocarbon group having 6 to 18 carbon atoms;

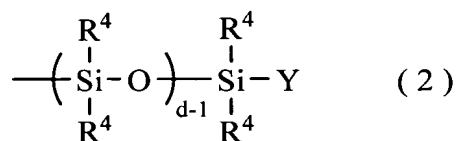
X: a divalent hydrocarbon group having 2 to 10 carbon atoms;

a and b: integers of 1 or more;

c: an integer of 0 or more;

the sum of a + b + c: an integer of 4 or more;

R<sup>3</sup>: a monovalent hydrocarbon group having 1 to 6 carbon atoms or a hydrogen atom, provided that R<sup>3</sup>s may be the same as or different from each other;



R<sup>4</sup>: a monovalent hydrocarbon group having 1 to 12 carbon atoms;

Y: a group selected from a methyl group, a vinyl group and R<sup>1</sup>;  
and

d: an integer of 2 to 500.

2. (Original) The composition of Claim 1, wherein the hydrolytic group-containing siloxane is contained in an amount of one part by weight based on 100 parts by weight of a base polymer having a curable functional group.

3. (Original) The composition of Claim 2, the composition further comprising a thermal conductive filler in an amount of 10 to 3000 parts by weight based on a total of 100 parts by weight of the hydrolytic group-containing siloxane and the curable functional group.

4. (Original) The composition of Claim 3, wherein the thermal conductive filler is selected from alumina, magnesium oxide, boron nitride, aluminum nitride, silica powder, metal powder, diamond, aluminum hydroxide and carbon and surface-treated products of these compounds.

5. (Currently Amended) The composition of ~~any one of Claims 1 to 4~~Claim 1, wherein the thermal conductive silicone composition is an addition reaction-curable type.